PRODUCT CHANGE NOTICE

Data Sheet Specification Change for Intersil Product ISL1534*

Refer to: PCN10085

Date: September 1, 2010



To: Our Valued Intersil Customers

Subject: Data Sheet Specification Change for Intersil Product ISL1534*

This notice is to inform you that Intersil is changing the data sheet specification for the listed ISL1534* products. The updates to the data sheet consist of the following:

- i) The Pinouts section has been updated to require the Thermal Pad to be connected to ground on sheet 2.
- ii) The Thermal Information section has been updated to include Thermal Resistance (θ_{JA}) values of 39°C/W for the QFN and 40°C/W for the HTSSOP package styles on sheet 3. The Package Power Dissipation curves for the QFN and HTSSOP packages in Figure 28 on sheet 10 were updated accordingly.
- iii) The Electrical Specifications table has been updated to change the Input High Voltage (V_{IH}) MIN limit from 2.0V to 2.2V on sheet 3.

Modifications to the data sheet specification incorporating the changes are complete. The updated data sheet is available upon request.

Products Affected: ISL1534IRZ ISL1534IRZ-T13 ISL1534IVEZ ISL1534IVEZ-T13

There has been no change to the device silicon. There will be no change in external marking of the packaged parts. Parts affected by this change are identifiable via Intersil's internal traceability system.

Intersil will take all necessary actions to conform to customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product electrically screened to the revised limit beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you immediately. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

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